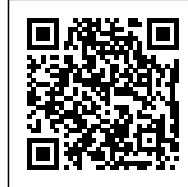


## FEEDING EQUIPMENT DIE EJECT UNIT

SKU: N/A

36.000,00 € – 60.000,00 € excl. VAT



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Categories: [Feeding equipment](#), [Modules](#)

## VARIATIONS


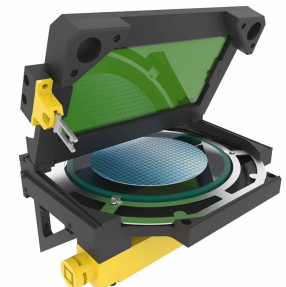
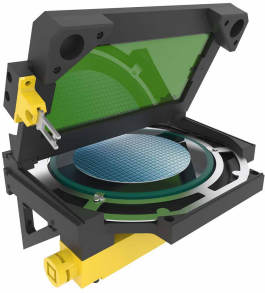

Image	SKU	Type	Options	Price
	S3-0086+30-0438	OurPlant X3	incl. wafer changer	60.000,00 € excl. VAT
	S3-0086+S3-0027	OurPlant X3	incl. single wafer loader	36.000,00 € excl. VAT

Image	SKU	Type	Options	Price
	S3-0085+S3-0027	OurPlant XTec	incl. single wafer loader	36.000,00 € excl. VAT
	S3-0085+30-0437	OurPlant XTec	incl. wafer changer	60.000,00 € excl. VAT

## BESCHREIBUNG

The Die Eject Unit has a needle system that ejects the components fixed to the film for transferring them to the assembly system. By replacing the manually exchangeable needle system and the wafer frame adapter, a wide range of components are processed from wafers of up to 8 inches in size. The speed of the ejecting needles is synchronized to the assembly system and is component-specific selectable.

The adapted wafer automatically loaded and unloaded by the wafer system.

The Eject Unit is available with a needle holder with lid and needle (needle-vacuum system) and a wafer adapter (selectable). By using special optional adaptations also Waffle-Packs can be processed on the module.

For loading of the wafers you can choose between a single wafer loader or an automatic wafer changer for up to 7 wafers.

## MORE INFORMATIONS

Max. wafer size in inch / mm	8 / 200
Voltage in V	24
Max. current in A	3
Communication interface	UNICAN

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